



Linux SLCNAND 开发指南

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1 概述

1.1 编写目的

介绍 Sunxi SLCNand mtd/ubi 驱动设计, 方便相关驱动和应用开发人员

1.2 适用范围

本设计适用于 UBI 方案 SLCNAND 平台

1.3 相关人员

Nand 模块开发人员, 及应用开发人员等

2 术语、缩略语及概念

MTD: (Memory Technology device) 是用于访问存储设备的 linux 子系统。本模块是 MTD 子系统的 flash 驱动部分

UBI: UBI 子系统是基于 MTD 子系统的，在 MTD 上实现 nand 特性的管理逻辑，向上屏蔽 nand 的特性

坏块 (Bad Block): 制作工艺和 nand 本身的物理性质导致在出厂和正常使用过程中都会产生坏块

3 流程设计

3.1 体系结构

NAND MTD/UBI 驱动主要包括 5 大组件，如下图：

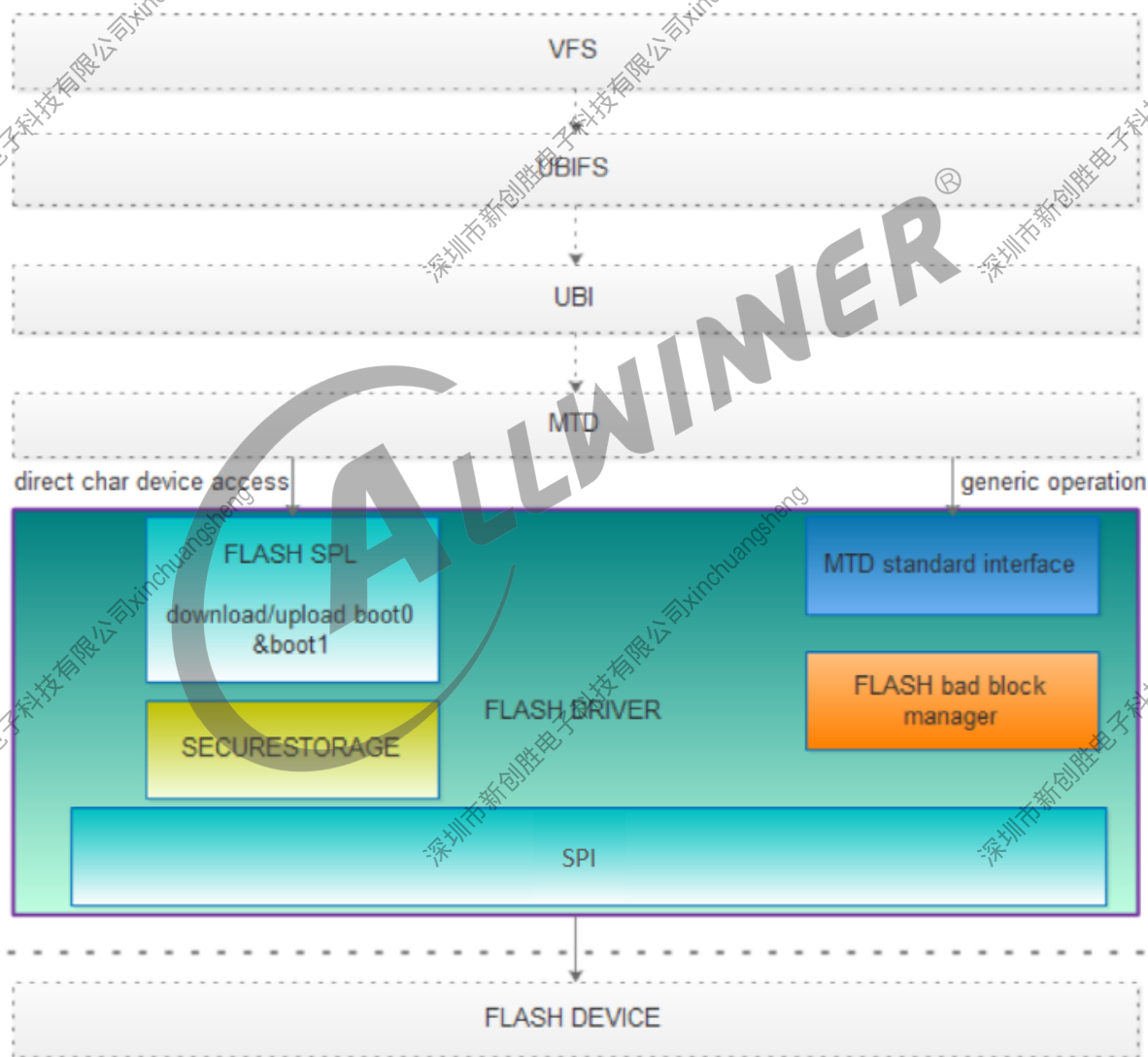


图 3-1: UBI 架构

说明：

MTD standard interface: 对接 MTD 层通用读写接口

FLASH bad block manager: 驱动层对 flash 坏块的管理

FLASH SPL: 主要是实现读写 boot0、boot1，可用于 ioctl 对 boot0、boot1 的升级

SECURESTORAGE: 主要是给上层提供私有数据的管理

SPI: HOST 端控制器层的实现

3.2 源码结构

3.2.1 内核版本 \leq Linux5.4

kernel 源码目录：linux-5.4/drivers/mtd/awnand/rawnand

```
├── Kconfig
├── Makefile
├── rawnand
│   ├── aw_rawnand_base.c
│   ├── aw_rawnand_bbt.c
│   ├── aw_rawnand_ids.c
│   ├── aw_rawnand_nfc.c
│   ├── aw_rawnand_nfc.h
│   ├── aw_rawnand_securestorage.c
│   ├── aw_rawnand_spl.c
│   ├── Kconfig
│   └── Makefile
```

头文件在：linux-5.4/include/linux/mtd/

```
include/linux/mtd/
├── aw-rawnand.h
```

3.2.2 内核版本 \geq Linux5.10

kernel 源码目录：bsp/drivers/mtd/awnand

```
├── Kconfig
├── Makefile
├── rawnand
│   ├── aw_rawnand_base.c
│   ├── aw_rawnand_bbt.c
│   ├── aw_rawnand_ids.c
│   ├── aw_rawnand_nfc.c
│   ├── aw_rawnand_nfc.h
│   ├── aw_rawnand_nfc_v0.c
│   ├── aw_rawnand_securestorage.c
│   ├── aw_rawnand_spl.c
│   ├── bootloader_update_demo.c
│   ├── Kconfig
│   └── Makefile
```

头文件在：bsp/include/linux/mtd/

aw-rawnand.h

3.3 关键数据定义

3.3.1 flash 设备信息数据结构

```
struct aw_nand_flash_dev {
    char *name;
    union {
        struct {
            uint8_t mfr_id;
            uint8_t dev_id;
        };
        uint8_t id[RAWNAND_MAX_ID_LEN];
    };
    int id_len;
    unsigned int dies_per_chip;
    /*main data size, eg. Page Size:(2K+64)byte ==> pagesize=2K byte,
    * sparesize=64byte*/
    unsigned int pagesize;
    unsigned int sparesize;
    unsigned int pages_per_blk;
    unsigned int blks_per_die;
    unsigned int access_freq;
    enum error_management badblock_flag_pos;
    unsigned int pe_cycles;
    unsigned int options;
};
```

说明：

- name: flash 的物料名字
- id: flash 的 id 码
- dies_per_chip: 每 chip 的 die 个数
- pagesize: 一个页大小
- sparesize: spare 区大小
- pages_per_blk: 每 block 有多少个 page
- access_freq: 工作频率
- badblock_flag_pos: 坏块标志存放在每个 block 的那个 page 中

1. PST_FIRST_PAGE
2. PST_FIRST_TWO_PAGES
3. PST_LAST_PAGE
4. PST_LAST_TWO_PAGES
5. PST_FIRST_AND_LAST_PAGES
6. PST_FIRST_TWO_AND_LAST_PAGES

- pe_cycles: flash 支持擦除次数
- options: 支持的操作

1. RAWNAND_ITF_SDR
2. RAWNAND_ITF_ONFI_DDR
3. RAWNAND_ITF_ONFI_DDR2
4. RAWNAND_ITF_TOGGLE_DDR
5. RAWNAND_ITF_TOGGLE_DDR2
6. RAWNAND_TOGGLE_SUPPORT_ONLY // TOGGLE only support
7. RAWNAND_ONFI_TIMING_MODE // ONFI timing mode, used in both asynchronous and synchronous mode
8. RAWNAND_ONFI_FEATURE_EXT_PARAM_PAGE // ONFI features
9. RAWNAND_MULTI_WRITE // Chip allow multi writes (80h – 11h ~ 80h – 10h)
10. RAWNAND_MULTI_READ // Chip allow multi reads
11. RAWNAND_MULTI_ERASE // Chip allow multi erase (60h-60h-d0h)
12. RAWNAND_MULTI_ONFI_ERASE // Chip allow onfi multi erase (60h-d1h ~ 60h- d0h)
13. RAWNAND_JEDEC_MULTI_WRITE // Chip allow multi writes (80h – 11h ~ 81h – 10h)
14. RAWNAND_ROW_ADDR_2 // Device needs 2rd row address cycle
15. RAWNAND_TOGGLE_DDR_TO_SDR // Default Toggle DDR1.0 , SDR need to set
16. RAWNAND_NFC_RANDOM // Open nfc randomizer

例子 (TC58NVG1S3HTA00) :

```
{
    .name = "TC58NVG1S3HTA00",
    .id = {0x98, 0xda, 0x90, 0x15, 0x76},
    .id_len = 5,
    .dies_per_chip = 1,
    .pagesize = SZ_2K,
    .sparesize = 128,
    .pages_per_blk = 64,
    .blks_per_die = 2048,
    .access_freq = 40,
    .badblock_flag_pos = PST_FIRST_PAGE,
    .pe_cycles = PE_CYCLES_100K,
    .options = RAWNAND_ITF_SDR | RAWNAND_NFC_RANDOM | RAWNAND_JEDEC_MULTI_WRITE |
        RAWNAND_MULTI_ERASE,
},
```

说明

详细的 flash 参数配置方法参考《NAND 物料 _ 调试指南》

3.3.2 flash chip 数据结构

```

struct aw_nand_chip {
    struct mutex lock;
    /*****
    * mtd layer
    * -----
    * simu chip
    * -----
    * chip
    * | --blkn---| --blkn+1--|
    * | (planeA) | (planeB) |
    * *****/
    struct mtd_info mtd;
#define SLC_NAND (0)
#define MLC_NAND (1)
    int type;

    uint8_t id[RAWNAND_MAX_ID_LEN];
    unsigned int dies;
#define MAX_DIES (2U)
    uint64_t diesize[MAX_DIES];
    int chips;
    uint64_t chipsize;
    uint64_t simu_chipsize;
    int chip_shift;
    int simu_chip_shift;
    int chip_pages;
    /*simulation is for multi, see line@48 rawnand multiplane layout.*/
    int simu_chip_pages;
    int chip_pages_mask;
    int simu_chip_pages_mask;

    /*main data size*/
    int pagesize;
    int simu_pagesize;
    /*main data size shift*/
    unsigned int pagesize_shift;
    unsigned int simu_pagesize_shift;
    int pagesize_mask;
    int simu_pagesize_mask;
    /*main data size + spare data size*/
    int real_pagesize;
    unsigned int erasesize;
    unsigned int simu_erasesize;
    unsigned int erase_shift;
    unsigned int simu_erase_shift;
    unsigned int erasesize_mask;
    unsigned int simu_erasesize_mask;
    unsigned int pages_per_blk_shift;
    unsigned int simu_pages_per_blk_shift;
    unsigned int pages_per_blk_mask;
    unsigned int simu_pages_per_blk_mask;
    int avalid_sparesize;
    int ecc_mode;
    int random;
    int row_cycles;
    enum error_management badblock_mark_pos;
    unsigned int pe_cycles;

```

```

unsigned int options;
int clk_rate;

int operate_boot0;
int boot0_ecc_mode;
int uboot_end;

struct select_chip selected_chip;
struct ce_info ceinfo[MAX_CHIPS];

struct aw_nand_chip_cache simu_chip_buffer;

struct rawnand_data_interface data_interface;
#define BBT_B_INVALID (2)
#define BBT_B_BAD (1)
#define BBT_B_GOOD (0)
uint8_t *bbt;
/*mark whether the corresponding bbt bit is updated*/
uint8_t *bbtd;

uint8_t bitflips;

void (*select_chip)(struct mtd_info *mtd, int chip);
bool (*dev_ready_wait)(struct mtd_info *mtd);
int (*dev_status)(struct mtd_info *mtd);

int (*block_bad)(struct mtd_info *mtd, int block);
int (*simu_block_bad)(struct mtd_info *mtd, int block);
int (*block_markbad)(struct mtd_info *mtd, int block);
int (*simu_block_markbad)(struct mtd_info *mtd, int block);
/*scan device to update bbt*/
int (*scan_bbt)(struct mtd_info *mtd);

int (*erase)(struct mtd_info *mtd, int page);
int (*multi_erase)(struct mtd_info *mtd, int page);

int (*write_page)(struct mtd_info *mtd, struct aw_nand_chip *chip,
uint8_t *mdata, int mlen, uint8_t *sdata, int slen, int page);
int (*multi_write_page)(struct mtd_info *mtd, struct aw_nand_chip *chip,
uint8_t *mdata, int mlen, uint8_t *sdata, int slen, int page);
int (*cache_write_page)(struct mtd_info *mtd, struct aw_nand_chip *chip,
uint8_t *mdata, int mlen, uint8_t *sdata, int slen, int page);
int (*read_page)(struct mtd_info *mtd, struct aw_nand_chip *chip,
uint8_t *mdata, int mlen, uint8_t *sdata, int slen, int page);
int (*multi_read_page)(struct mtd_info *mtd, struct aw_nand_chip *chip,
uint8_t *mdata, int mlen, uint8_t *sdata, int slen, int page);
int (*read_page_spare)(struct mtd_info *mtd, struct aw_nand_chip *chip,
uint8_t *sdata, int slen, int page);

int (*write_boot0_page)(struct mtd_info *mtd, struct aw_nand_chip *chip,
uint8_t *mdata, int mlen, uint8_t *sdata, int slen, int page);
int (*read_boot0_page)(struct mtd_info *mtd, struct aw_nand_chip *chip,
uint8_t *mdata, int mlen, uint8_t *sdata, int slen, int page);

int (*setup_read_retry)(struct mtd_info *mtd, struct aw_nand_chip *chip);
int (*setup_data_interface)(struct mtd_info *mtd, struct aw_nand_chip *chip,
int chipnr, const struct rawnand_data_interface *conf);

```

```
struct aw_nand_flash_dev *dev;

void *priv;
struct list_head node;
};
```

此结构定义了 flash chip 层的物理模型数据结构以及 chip 层对 flash 的操作接口。

- type: raw nand 的类型 (SLC_NAND、MLC_NAND)
- pagesize: 页大小
- simu_pagesize: super page 大小
- int real_pagesize: main data size + spare data size
- erasesize: 擦除大小
- simu_erasesize: super block 擦除大小
- pages_per_blk_shift: block 转 page 数的移位次数
- ecc_mode: ecc 模式

1. BCH_16
2. BCH_24
3. define BCH_28
4. define BCH_32
5. define BCH_40
6. define BCH_48
7. define BCH_56
8. define BCH_60
9. define BCH_64 (8)

- random: 随机化功能
- options: 支持的操作

函数指针对应物理层接口说明

3.3.3 ubi_ec_hdr

```
struct ubi_ec_hdr {
    __be32 magic;
    __u8 version;
    __u8 padding1[3];
    __be64 ec; /* Warning: the current limit is 31-bit anyway! */
    __be32 vid_hdr_offset;
    __be32 data_offset;
    __be32 image_seq;
```

```
__u8 padding2[32];
__be32 hdr_crc;
}__packed;
```

@magic: erase counter header magic number (%UBI_EC_HDR_MAGIC)

@version: version of UBI implementation which is supposed to accept this UBI image

@padding1: reserved for future, zeroes

@ec: the erase counter

@vid_hdr_offset: where the VID header starts

@data_offset: where the user data start

@image_seq: image sequence number

@padding2: reserved for future, zeroes

@hdr_crc: erase counter header CRC checksum

EC: Erase Count, 记录块的擦除次数, 在 ubiattach 的时候指定一个 mtd, 如果 PEB 上没有 EC, 则用平均的 EC 值, 写入 EC 值只有在擦除的时候才会增加 1

3.3.4 ubi_vid_hdr

```
struct ubi_vid_hdr {
    __be32 magic;
    __u8 version;
    __u8 vol_type;
    __u8 copy_flag;
    __u8 compat;
    __be32 vol_id;
    __be32 lnum;
    __u8 padding1[4];
    __be32 data_size;
    __be32 used_ebs;
    __be32 data_pad;
    __be32 data_crc;
    __u8 padding2[4];
    __be64 sqnum;
    __u8 padding3[12];
    __be32 hdr_crc;
}__packed;
```

@magic: volume identifier header magic number (%UBI_VID_HDR_MAGIC)

@version: UBI implementation version which is supposed to accept this UBI image (%UBI_VERSION)

@vol_type: volume type (%UBI_VID_DYNAMIC or %UBI_VID_STATIC)

@copy_flag: if this logical eraseblock was copied from another physical eraseblock (for wear-leveling reasons)

@compat: compatibility of this volume(%0, %UBI_COMPAT_DELETE, %UBI_COMPAT_IGNORE, %UBI_COMPAT_PRESERVE, or %UBI_COMPAT_REJECT)

@vol_id: ID of this volume

@lnum: logical eraseblock number

@padding1: reserved for future, zeroes

@data_size: how many bytes of data this logical eraseblock contains

@used_ebs: total number of used logical eraseblocks in this volume

@data_pad: how many bytes at the end of this physical eraseblock are not used

@data_crc: CRC checksum of the data stored in this logical eraseblock

@padding2: reserved for future, zeroes

@sqnum: sequence number

@padding3: reserved for future, zeroes

@hdr_crc: volume identifier header CRC checksum

参数说明

@sqnum 是创建此 VID 头时的全局序列计数器的值。每次 UBI 写一个新的 VID 头到 flash 时，全局序列计数器都会增加，比如当它将一个逻辑的 eraseblock 映射到一个新的物理的 eraseblock 时。全局序列计数器是一个无符号 64 位整数，我们假设它永远不会溢出。@sqnum(序列号) 用于区分新旧版本的逻辑擦除块。

有两种情况，可能有多个物理 eraseblock 对应同一个逻辑 eraseblock，即在卷标识头中有相同的 **@vol_id** 和 **@lnum** 值。假设我们有一个逻辑的擦除块 L，它被映射到物理的擦除块 P。

1. 因为 UBI 可以异步擦除物理上的擦除块，所以可能出现以下情况:L 被异步擦除，所以 P 被安排擦除，然后 L 被写入，即。映射到另一个物理的擦除块 P1，所以 P1 被写入，然后不干净的重启发生。结果-有两个物理的 eraseblock P 和 P1 对应同一个逻辑的 eraseblock L。但是 P1 的序列号更大，所以 UBI 在连接 flash 时选择 P1。
2. UBI 不时地将逻辑擦除块移动到其他物理擦除块，以达到损耗均衡的目的。例如，如果 UBI 将 L 从 P 移动到 P1，在 P 被物理擦除之前会发生不干净的重启，有两个物理擦除块 P 和 P1 对应于 L, UBI 必须在 flash 连接时选择其中一个。**@sqnum** 字段表示哪个 PEB 是原始的 (显然 P 的 **@sqnum** 更低) 和副本。但是选择具有更高序列号的物理擦除块是不够的，因为不干净的重启可能发生在复制过程的中间，因此 P 中的数据被损坏 (P->P1 没复制完)。仅仅选择序号较低的物理擦除块是不够的，因为那里的数据可能很旧 (考虑在复制之后向 P1 添加更多数据)

的情况)。此外，不干净的重启可能发生在擦除 P 刚开始的时候，所以它会导致不稳定的 P，“大部分”是 OK 的，但仍然有不稳定的情况。

UBI 使用 **@copy_flag** 字段表示这个逻辑擦除块是一个副本。UBI 还计算数据的 CRC，当数据被移动时，并将其存储在副本 (P1) 的 **@data_crc** 字段。因此，当 UBI 需要从两个 (P 或 P1) 中选择一个物理擦除块时，会检查新块 (P1) 的 **@copy_flag**。如果它被清除，情况就简单了，新的就会被选中。如果设置了该值，则检查副本 (P1) 的数据 CRC。如果 CRC 校验和是正确的，这个物理擦除块被选中 (P1)。否则，将选择较老的 P。

如果是静态卷，**@data_crc** 字段包含逻辑擦除块内容的 CRC 校验和。对于动态卷，它不包含 CRC 校验和规则。唯一的例外情况是，当物理擦除块的数据被磨损均衡子系统移动时，磨损均衡子系统计算数据 CRC，并将其存储在 **@data_crc** 字段中。

@used_ebs 字段仅用于静态卷，它表示该卷的数据需要多少个擦除块。对于动态卷，这个字段不被使用并且总是包含 0。

@data_pad 在创建卷时使用对齐参数计算。因此，**@data_pad** 字段有效地减少了该卷的逻辑擦除块的大小。当一个人在 UBI 卷上使用面向块的软件 (比如，cramfs) 时，这是非常方便的。

LEB 与 PEB

block size = 128k 为例

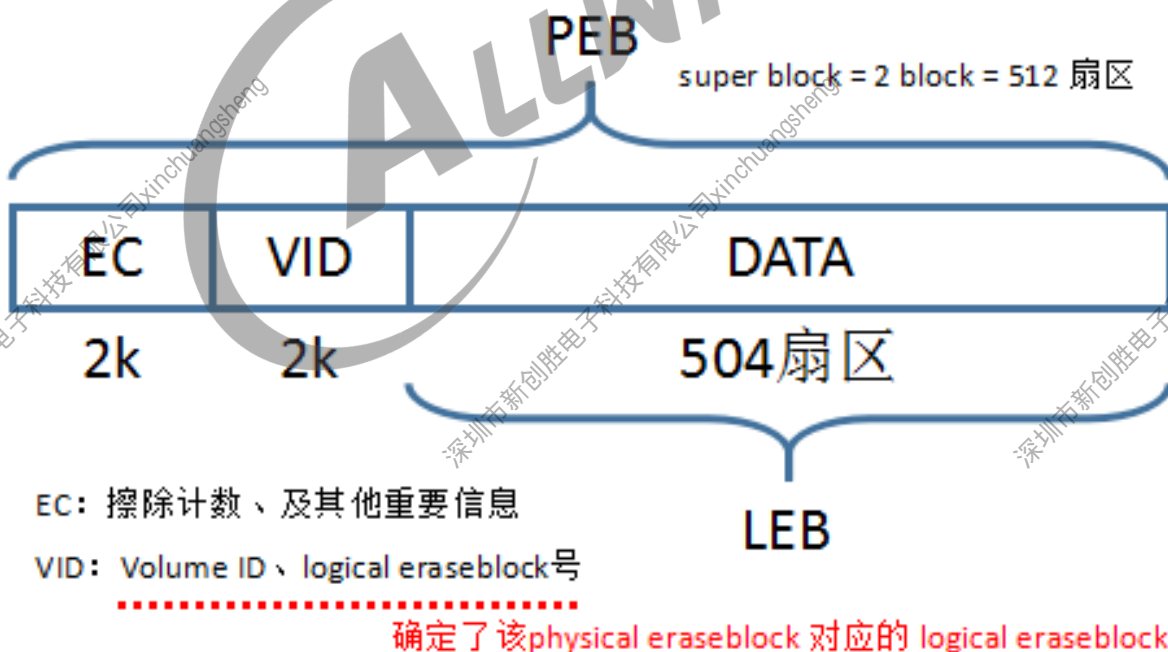


图 3-2: PEB-LEB

3.4 关键接口说明

3.4.1 MTD 层接口

3.4.1.1 aw_rawnand_mtd_erase

```
static int aw_rawnand_mtd_erase(struct mtd_info *mtd, struct erase_info *instr)
```

description: mtd erase interface

@mtd: MTD device structure

@instr: erase operation description structure

return: success return 0, fail return fail code

3.4.1.2 aw_rawnand_mtd_read

```
static int aw_rawnand_mtd_read(struct mtd_info *mtd, loff_t from, size_t len, size_t *retlen, u_char *buf)
```

description: mtd read interface

@mtd: MTD device structure

@from: offset to read from MTD device

@len: data len

@retlen: had read data len

@buf: data buffer

return: success return max_bitflips, fail return fail code

3.4.1.3 aw_rawnand_mtd_read_oob

```
static int aw_rawnand_mtd_read_oob(struct mtd_info *mtd, loff_t from, struct mtd_oob_ops *ops)
```

description: mtd read data with oob

@mtd: MTD device structure

@ops: oob operation description structure

return: success return max_bitflips, fail return fail code

3.4.1.4 aw_rawnand_mtd_write

```
static int aw_rawnand_mtd_write(struct mtd_info *mtd, loff_t to, size_t len, size_t *retlen, const u_char *buf)
```

description: mtd write data interface

@to: offset to MTD device

@len: want write data len

@retlen: return the written len

@buf: data buffer

return: success return 0, fail return code fail

3.4.1.5 aw_rawnand_mtd_write_oob

```
static int aw_rawnand_mtd_write_oob(struct mtd_info *mtd, loff_t to, struct mtd_oob_ops *ops)
```

description: write data with oob

@mtd: MTD device structure

@to: offset to MTD device

@ops: oob operation description structure

return: success return 0, fail return code fail

3.4.1.6 aw_rawnand_mtd_block_isbad

```
static int aw_rawnand_mtd_block_isbad(struct mtd_info *mtd, loff_t ofs)
```

description: check block is badblock or not

@mtd: MTD device structure

@ofs: offset the mtd device start (align to simu block size)

return: true if the block is bad, or false if the block is good

3.4.1.7 aw_rawnand_mtd_block_markbad

```
static int aw_rawnand_mtd_block_markbad(struct mtd_info *mtd, loff_t ofs)
```

description: mark block at the given offset as bad block

@mtd: MTD device structure

@ofs: offset the mtd device start

return: success to mark return 0, or fail return fail code.

3.4.2 物理层接口

3.4.2.1 aw_rawnand_chip_read_page

```
int aw_rawnand_chip_read_page(struct mtd_info *mtd, struct aw_nand_chip *chip,  
uint8_t *mdata, int mlen, uint8_t *sdata, int slen, int page)
```

description: Read physics on a page

@mtd: MTD device structure

@chip: See 3.3.2

@mdata: 要读出数据缓存

@mlen: 要读出数据长度

@sdata: 要读出 spare 区数据缓存

@slen: 要读出 spare 区数据长度

@page: 要读取的目标 page

return: zero on success, else a negative error code

3.4.2.2 aw_rawnand_chip_write_page

```
int aw_rawnand_chip_write_page(struct mtd_info *mtd, struct aw_nand_chip *chip,  
uint8_t *mdata, int mlen, uint8_t *sdata, int slen, int page)
```

description: Write physics on a page

@mtd: MTD device structure

@chip: See 3.3.2

@mdata: 要读出数据缓存

@mlen: 要读出数据长度

@sdata: 要读出 spare 区数据缓存

@slen: 要读出 spare 区数据长度

@page: 要读取的目标 page

return: zero on success, else a negative error code

3.4.2.3 aw_rawnand_chip_erase

```
int aw_rawnand_chip_erase(struct mtd_info *mtd, int page)
```

description: Erase physics on a block

@mtd: MTD device structure

@page: 擦除 page 对应的 block

return: zero on success, else a negative error code

3.4.2.4 aw_rawnand_chip_block_bad

```
int aw_rawnand_chip_block_bad(struct mtd_info *mtd, int block)
```

description: aw_rawnand_chip_simu_block_bad - read bad block marker from the chip

@mtd: MTD device structure

@block: simu block offset from device start simu block

return: BBT_B_BAD return 1, BBT_B_GOOD return 0

3.4.2.5 aw_rawnand_chip_block_markbad

```
int aw_rawnand_chip_block_markbad(struct mtd_info *mtd, int block)
```

description: aw_rawnand_chip_block_markbad - mark a block bad in mark pos and update bbt&bbtd

@mtd: MTD device structure

@block: block offset from device start

return: zero on success, else a negative error code

3.4.3 Uboot 应用接口

3.4.3.1 sunxi_flash_nand_probe

```
static int sunxi_flash_nand_probe(void)
```

description: MTD layer and SPINAND || RAWNAND initialization, Set the storage type.

return: zero on success, else a negative error code.

3.4.3.2 sunxi_flash_nand_init

```
static int sunxi_flash_nand_init(int boot_mode, int res)
```

description: MTD layer and SPINAND || RAWNAND initialization.

boot_mode: Working mode

res: The default is 0

return: zero on success, else a negative error code.

3.4.3.3 sunxi_flash_nand_exit

```
int spinand_mtd_exit(void)
```

description: Release registration is a resource for applications.

return: zero on success, else a negative error code.

3.4.3.4 sunxi_flash_nand_write

```
static int sunxi_flash_nand_write(uint start_block, uint nblock, void *buffer)
```

description: mtd write data interface.

start_block: want write start block

nblock: want write block count

buffer: data buffer

return: zero on success, else a negative error code.

3.4.3.5 sunxi_flash_nand_read

```
static int sunxi_flash_nand_read(uint start_block, uint nblock, void *buffer)
```

description: mtd readdata interface.

start_block: want read start block

nblock: want read block count

buffer: data buffer

return: zero on success, else a negative error code.

3.4.3.6 sunxi_flash_nand_erase

```
static int sunxi_flash_nand_erase(int erase, void *mbr_buffer)
```

description: erase boot || partition data.

erase: erase flag

buffer: The default is NULL

return: zero on success, else a negative error code.

3.4.3.7 sunxi_flash_nand_force_erase

```
int spinand_mtd_force_erase(void)
```

description: erase boot & partition data.

return: zero on success, else a negative error code.

3.4.3.8 sunxi_flash_nand_flush

```
int ubi_nand_flush(void)
```

description: Flush physical cache data to flash.

return: zero on success, else a negative error code.

3.4.3.9 sunxi_flash_nand_download_spl

```
static int sunxi_flash_nand_download_spl(unsigned char *buf, int len, unsigned int ext)
```

description: write boot0.

buf: boot0 data buffer

len: boot0 data len

ext: storage type

return: zero on success, else a negative error code.

3.4.3.10 sunxi_flash_nand_download_toc

```
static int sunxi_flash_nand_download_toc(unsigned char *buf, int len, unsigned int ext)
```

description: write uboot.

buf: uboot data buffer

len: uboot data len

ext: storage type

return: zero on success, else a negative error code.

4 模块配置

4.1 uboot 模块配置

Device Drivers-->Sunxi flash support-->
[*]Support sunxi nand devices
[*]Support sunxi nand ubifs devices
[*]Support COMM NAND V1 interface

如下图：

```
--- Sunxi flash support
[*] Support sunxi nand devices
[*] Support sunxi nand ubifs devices
[ ] Support COMM NAND interface
[*] Support COMM NAND V1 interface
[ ] Support sunxi spinor devices
[ ] support sunxi sdmmc devices
```

图 4-1: u-boot-spinand-menuconfig

4.2 kernel 模块配置

4.2.1 内核版本 ≤Linux5.4

Device Drivers-->Memory Technology Device(MTD) support-->sunxi-nand

```

[ ] Retain master device when partitioned
RAM/ROM/Flash chip drivers --->
Mapping drivers for chip access --->
Self-contained MTD device drivers --->
< > OneNAND Device Support ----
< > Raw/Parallel NAND Device Support ----
< > SPI NAND device Support ----
[ ] sunxi-nand --->
LPDDR & LPDDR2 PCM memory drivers --->
< > SPI-NOR device support ----
[*] Enable UBI - Unsorted block images --->
< > HyperBus support ----

```

图 4-2: UBI

```

sunxi-nand
s ---> (or empty submenus ----). Highlighted letters are hotkeys. Pressing <Y>
end: [*] built-in [ ] excluded <M> module <A> module capable

<A> Awnand Choice (Allwinner MTD SPINAND Device Support) ---->
[ ] create pstore mtd partition for aw ubi spinand
[ ] check crc16 for each page on spinand physical layer
[*] enable simulate multiplane

```

图 4-3: ker_nand-cfg

```

AWNAND CHOICE
Use the arrow keys to navigate this window or press the
hotkey of the item you wish to select followed by the <SPACE
BAR>. Press <?> for additional information about this

( ) Allwinner MTD SPINAND Device Support
[X] Allwinner MTD RAWNAND Device Support

<Select> < Help >

```

图 4-4: ker_spinand

File systems-->Miscellaneous filesystems-->

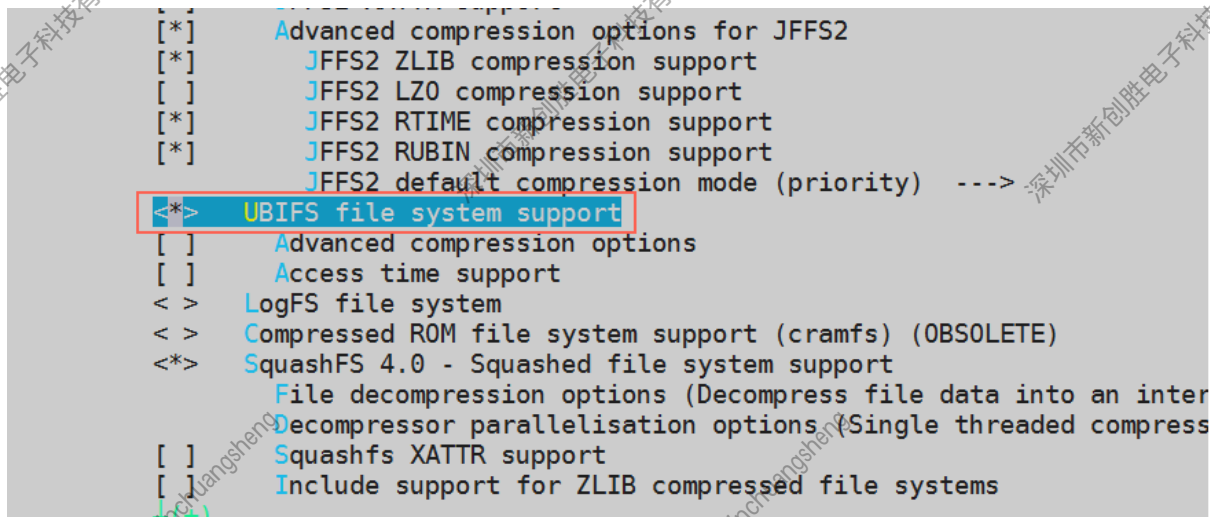


图 4-5: menuconfig_spinand_ubifs

4.2.2 内核版本 \geq Linux5.10

Allwinner BSP --->Device Drivers --->Memory Technology Device(MTD) support

```

--- Memory Technology Device (AW_MTD) support
--> (or empty submenus ----). Highlighted letters are hotkeys. Pressing <y>
[*] built-in [ ] excluded <M> module < > module capable

--- Memory Technology Device (AW_MTD) support
< > MTD tests support (DANGEROUS)
Partition parsers --->
*** User Modules And Translation Layers ***
<*> Caching block device access to MTD devices
< > FTL (Flash Translation Layer) support
< > NFTL (NAND Flash Translation Layer) support
< > INFTL (Inverse NAND Flash Translation Layer) support
< > Resident Flash Disk (Flash Translation Layer) support
< > NAND SSFDC (SmartMedia) read only translation layer
< > SmartMedia/xD new translation layer
< > Log panic/oops to an MTD buffer
< > Swap on MTD device support
[ ] Retain master device when partitioned
RAM/ROM/Flash chip drivers --->
Self-contained MTD device drivers --->
LPDDR & LPDDR2 PCM memory drivers --->
< > SPI NOR device support
-* Enable UBI - Unsorted block images --->
< > HyperBus support
< > Allwinner MTD SPINAND Device Support
<*> Allwinner MTD RAWNAND Device Support
[ ] Kernel images are stored on physical partitions
[ ] create pstore mtd partition for aw ubi rawnand
[*] enable simulate multiplane
[ ] upload boot0 to check after download boot0 img
[ ] upload uboot to check after download uboot img

```

图 4-6: rawnand-config

Allwinner BSP --->Device Drivers --->SPI Drivers

```

SPI Drivers
--> (or empty submenus ----). Highlighted letters are hotkeys. Pre
[*] built-in [ ] excluded <M> module < > module capable

<*> SPI Support for Allwinner SoCs

```

图 4-7: linux5.10-menuconfig-spi

Allwinner BSP --->Device Drivers --->DMA Drivers

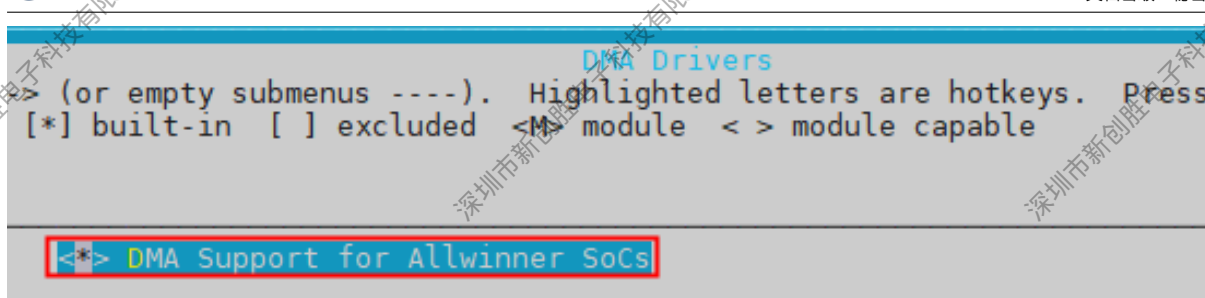


图 4-8: linux5.10-menuconfig-dma

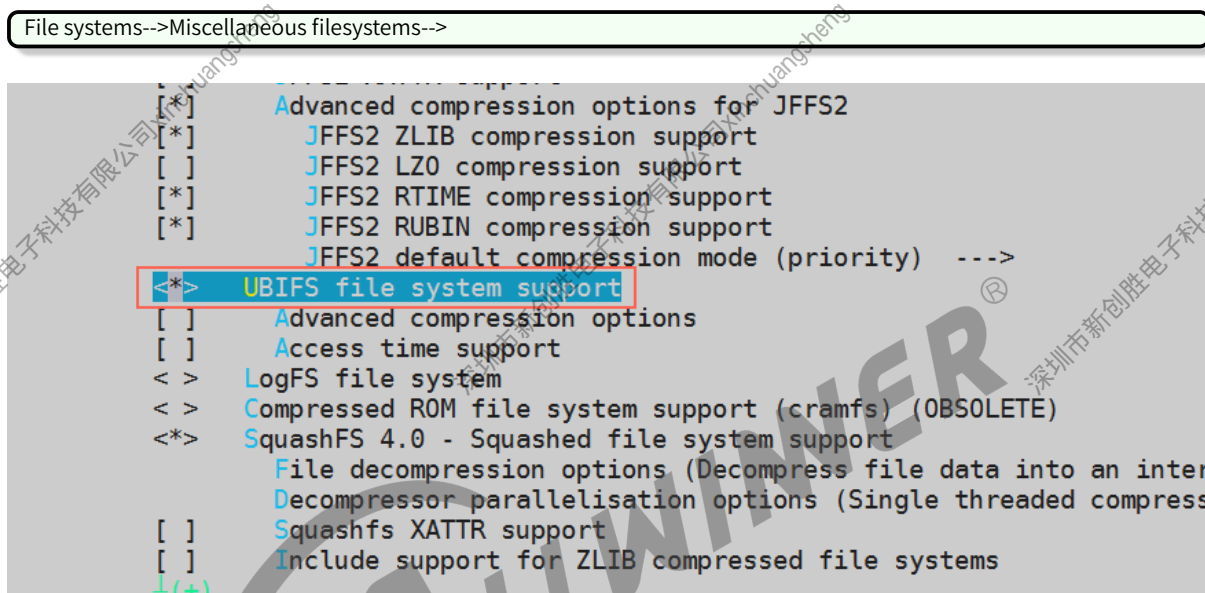


图 4-9: menuconfig_spinand_ubifs

4.3 env.cfg

在 env.cfg 中添加修改下值，setargs_nand_ubi 先 copy 一份 setargs_nand 再添加对应变量

路径：device/config/chips/平台（v833）/configs/default/env.cfg

```
nand_root=ubi0_4
mtd_name=sys
rootfstype=ubifs,rw
setargs_nand_ubi=setenv bootargs ubi.mtd=${mtd_name}
                        rootfstype=${rootfstype}
```

图 4-10: build-mkcmd

4.4 Soc 级设备树配置

Soc 级设备树保存的是该类芯片所有平台的模块配置，不同内核版本 Soc 级设备树所在路径不同，但对于每一个 nand 控制器来说，在设备树中配置参数相似，平台设备树文件路径为：

- 内核版本 \leq Linux-5.4

kernel/linux-x.x/arch/armxx/boot/dts/sunxi/CHIP.dtsi(CHIP为研发代号，如sun50iw10p1等)。

- 内核版本 \geq Linux5.10

bsp/configs/内核版本/CHIP.dtsi(CHIP为研发代号，如sun55iw3p1等)：

```
nand0:nand0@04011000 {
    compatible = "allwinner,sun55iw3-nand";
    device_type = "nand0";
    reg = <0x0 0x04011000 0x0 0x1000>; /* nand0 */
    interrupts = <GIC_SPI 38 IRQ_TYPE_LEVEL_HIGH>;
    clocks = <&ccu CLK_PLL_PERI1_400M>,
        <&ccu CLK_NAND0_CLK0>,
        <&ccu CLK_NAND0_CLK1>,
        <&ccu CLK_NAND0>,
        <&ccu CLK_NAND_MBUS_GATE>;
    clock-names = "pll_periph", "mclk", "ecc", "bus", "mbus";
    resets = <&ccu RST_BUS_NAND>;
    reset-names = "rst";
    nand0_regulator1 = "none";
    nand0_regulator2 = "none";
    nand0_cache_level = <0x55aaaa55>;
    nand0_flush_cache_num = <0x55aaaa55>;
    nand0_capacity_level = <0x55aaaa55>;
    nand0_id_number_ctl = <0x55aaaa55>;
    nand0_print_level = <0x55aaaa55>;
    nand0_p0 = <0x55aaaa55>;
    nand0_p1 = <0x55aaaa55>;
    nand0_p2 = <0x55aaaa55>;
    nand0_p3 = <0x55aaaa55>;
    chip_code = "sun55iw3";
    boot_crc = "okay";
    status = "okay";
};
```

4.5 board 级设备树配置

配置文件路径为：/device/config/chips/{IC}/configs/{BOARD}/board.dts, 用于保存每一个板级平台设备差异化的信息的补充。里面的配置信息会覆盖上面 Soc 级默认配置信息。

4.5.1 引脚 PINMUX 配置

```
nand0_pins_default: nand0@0 {
    pins = "PC0", "PC1", "PC2", "PC5",
           "PC8", "PC9", "PC10", "PC11",
           "PC12", "PC13", "PC14", "PC15",
           "PC16";
    function = "nand0";
    drive-strength = <30>; //IO驱动能力
};

nand0_pins_rb: nand0@1 {
    pins = "PC4", "PC6", "PC3", "PC7";
    function = "nand0";
    drive-strength = <30>;
    bias-pull-up; /* only RB&CE should be pulled up */
};

nand0_pins_sleep: nand0@2 {
    pins = "PC0", "PC1", "PC2", "PC3",
           "PC4", "PC5", "PC6", "PC7",
           "PC8", "PC9", "PC10", "PC11",
           "PC12", "PC13", "PC14", "PC15",
           "PC16";
    function = "io_disabled";
    drive-strength = <10>;
};
```

4.5.2 nand 设备节点配置

```
&nand0 {
    compatible = "allwinner,sun55iw3-nand";
    device_type = "nand0";
    pinctrl-names = "default", "sleep";
    pinctrl-0 = <&nand0_pins_default &nand0_pins_rb>;
    pinctrl-1 = <&nand0_pins_sleep>;
    nand0_regulator1 = "vcc-nand";
    nand0_regulator2 = "none";
    chip_code = "sun55iw3";
    status = "okay";
};
```

设备树配置参数说明：

配置项	功能
pinctrl-0	默认的引脚配置状态，详见与 CHIP.dtsi 同级目录下的 CHIP-pinctrl.dtsi，用户可通过 pinctrl 中修改引脚驱动能力，上下拉，一般 nand CE、RB 引脚默认上拉
pinctrl-1	休眠时的引脚状态，一般不需要用户修改
nand0_regulator1	VCC-NAND 电源配置，根据实际硬件原理图修改，可配置在对应的 board.dts 中

配置项	功能
nand0_regulator2	VCCQ 电源配置，根据实际硬件原理图修改，可配置在对应的 board.dts 中
nand0_cache_level	默认 0x55aaaa55，用于调整算法 cache 数量，不建议用户修改
nand0_capacity_level	默认 0x55aaaa55，每个分区的保留比例是十分之一；改为 1: 1. 每个分区的保留比例由十分之一改为十三分之一。2. 重负载下随机写速度会降低。不建议用户修改
nand0_flush_cache_num	默认 0x55aaaa55，不建议用户修改
nand0_id_number_ctl	默认 0x55aaaa55，修改 two plane, interleave、dual channel 配置，不建议用户修改
nand0_print_level	默认 0x55aaaa55，修改算法打印等级，不建议用户修改
nand0_px	配合 nand0_id_number_ctl 一起使用，修改 flash 频率，two plane, interleave、dual channel 配置，不建议用户修改
chip_code	绑定平台，不建议用户修改
boot_crc	“disabled” 关闭启动检测逻辑页 crc 功能，默认打开

5 使用案例

在 ubi 卷上模拟 mtddblock 设备，挂载块设备文件系统

1. 在 sys_partition*.fex 中添加分区（大小要求对齐到 504 扇区）；
2. 在内核配置中打开 CONFIG_MTD_BLOCK、CONFIG_MTD_UBI_GLUEBI；
3. 编译、打包、烧录固件；
4. 对应的块设备为/dev/mtddblock*，具体序号可以从后往前对应 sys_partition*.fex 文件中的分区；
5. 如果 sys_partition*.fex 中没有指定 downloadfile，挂载前需要格式化：mkfs.vfat /dev/mtddblock12
6. 挂载分区：mkdir /mnt/test1 & mount -t vfat /dev//dev/mtd12 /mnt/test1；

6 常见问题排查

参考《NAND 量产问题 _ 排查指南》和《NAND 硬件 _ 排查指南 v0.4》




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